

Prognostics of Power Electronic Modules Using Machine Learning

Mehdi Ghrabli^{1,2,4}, Mounira Bouarroudj^{2,3}, Ludovic Chamoin^{1,4}, Emanuel Aldea^{1,2}

1: Paris-Saclay University 2: SATIE Laboratory, CNRS, ENS Paris-Saclay 3: Paris-Est Créteil University

4: LMPS Laboratory Université Paris-Saclay, Centrale Supélec, CNRS, ENS Paris-Saclay

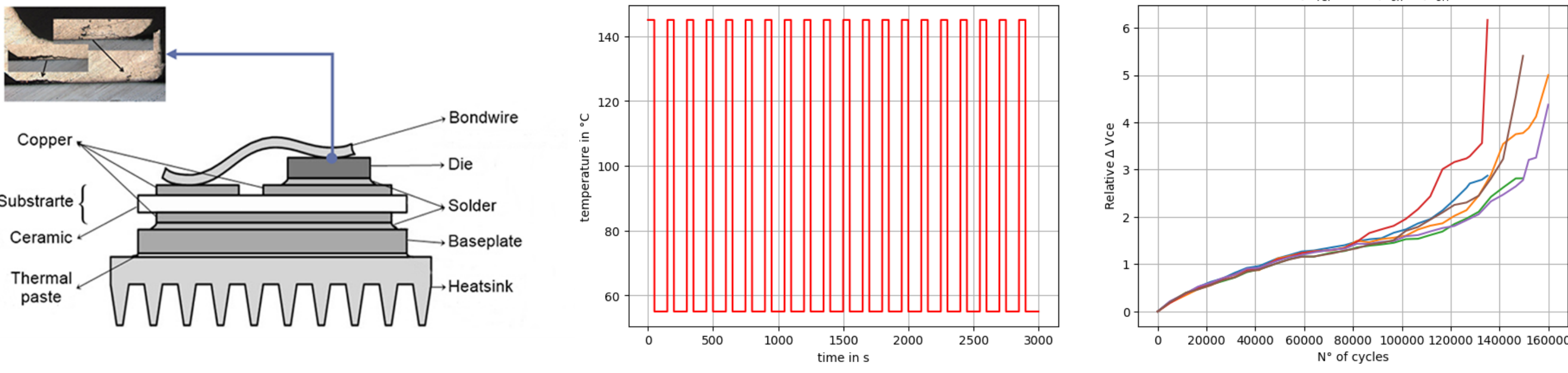
mehdi.ghrabli@ens-paris-saclay.fr



Systèmes et Applications des Technologies de l'Information et de l'Énergie - UMR 8029

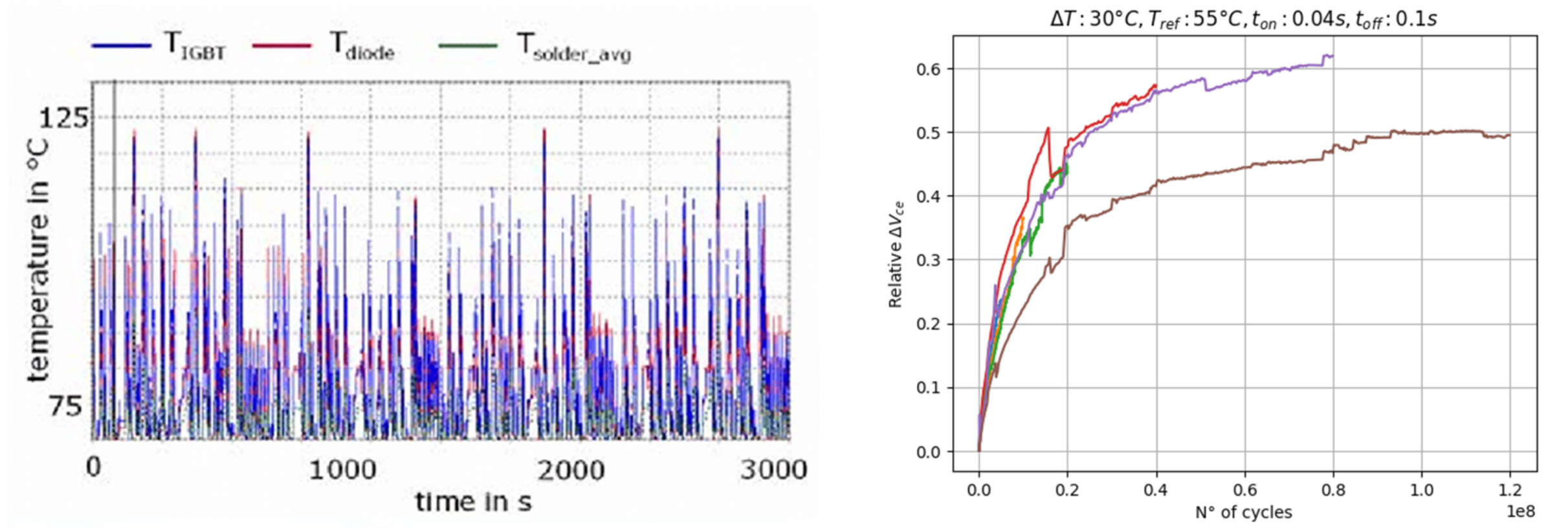
1. Power Electronics Prognostics in Context

- Power electronic modules fail gradually due to constraints caused by temperature variation.
- Bondwire degradation induced by self heating is a prevalent cause of failure.
- Experimental assessment consists of cyclical injections of a current I to the module, causing a temperature swing of ΔT for a duration t_{on} and relaxing it for a duration t_{off} .
- Health state is monitored by measuring the voltage V_{ce} . A relative increase ΔV_{ce} beyond a threshold ($\approx 5\%$) indicates failure.



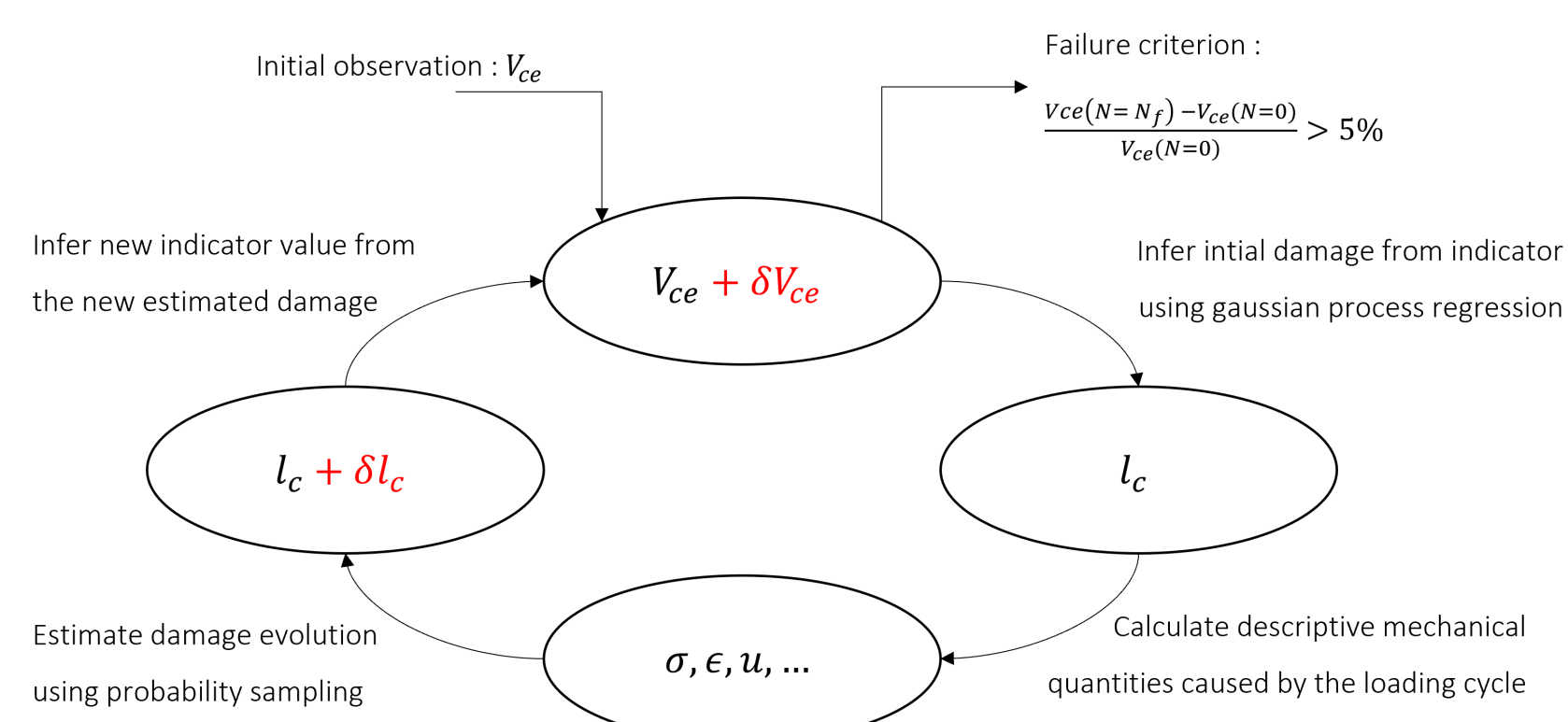
2. Key Challenges in Power Electronics

- Real-life loading profiles are complex, with variability in magnitude ΔT and durations t_{on} and t_{off} .
- Failure under realistic conditions is slow, which limits experiments (slow evolution of V_{ce} for $\Delta T = 30^\circ C$).
- Conventional approaches are limited by sparse data, restrictive assumptions, and computational inefficiency.

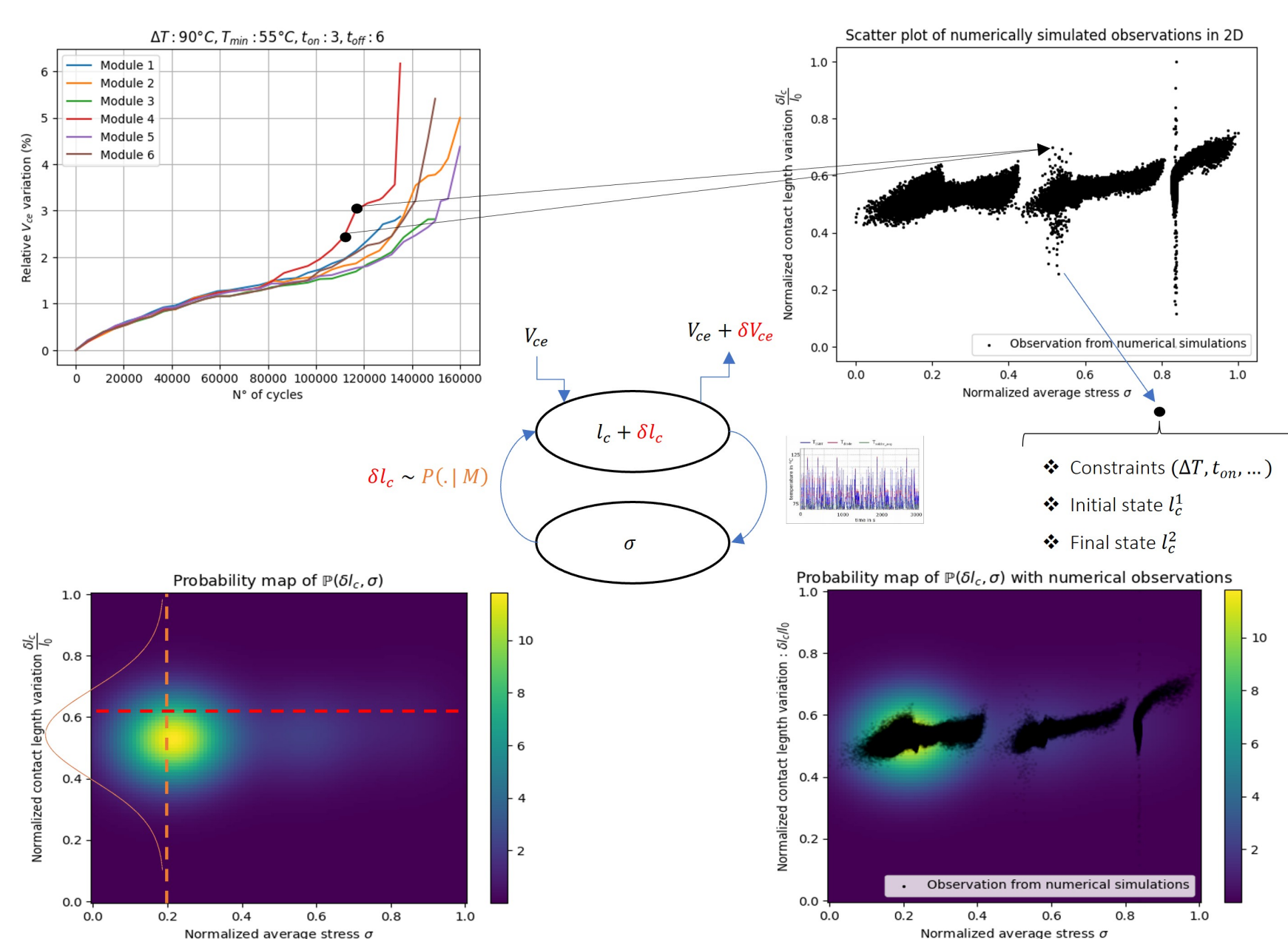


3. Modeling Degradation

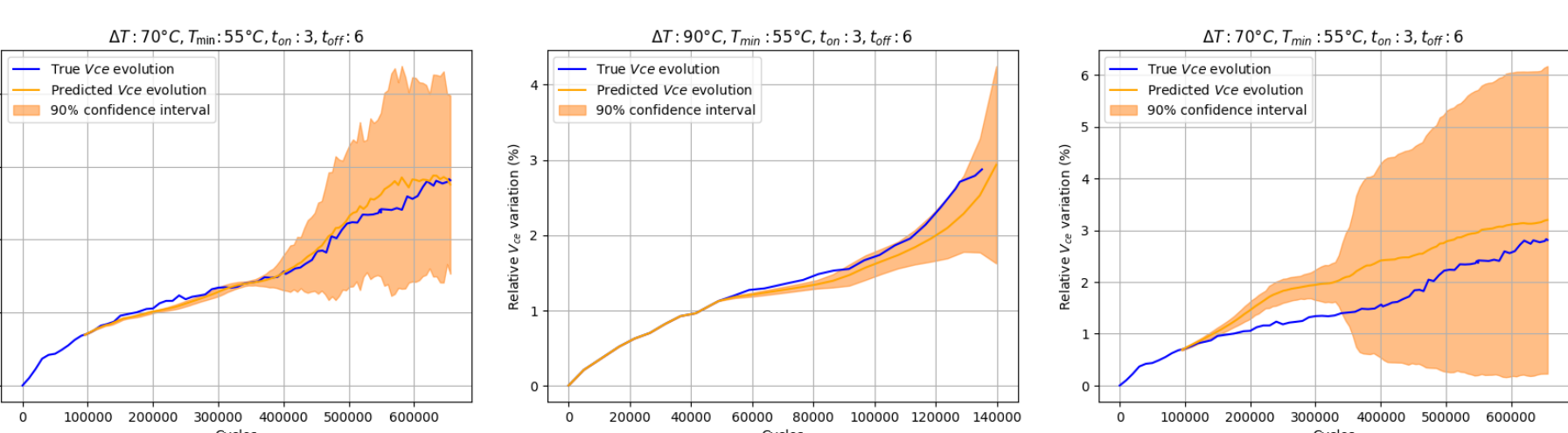
- Recurrent approach which infers damage increments caused by each loading cycle, thus accounting for variability.



- Damage is inferred using a probability density function $\mathbb{P}(\delta l_c | M)$ giving the probability that a degradation δl_c occurs under a given observation M defined by the module's state (current degradation) and a set of mechanical quantities describing the effect of the loading cycle.

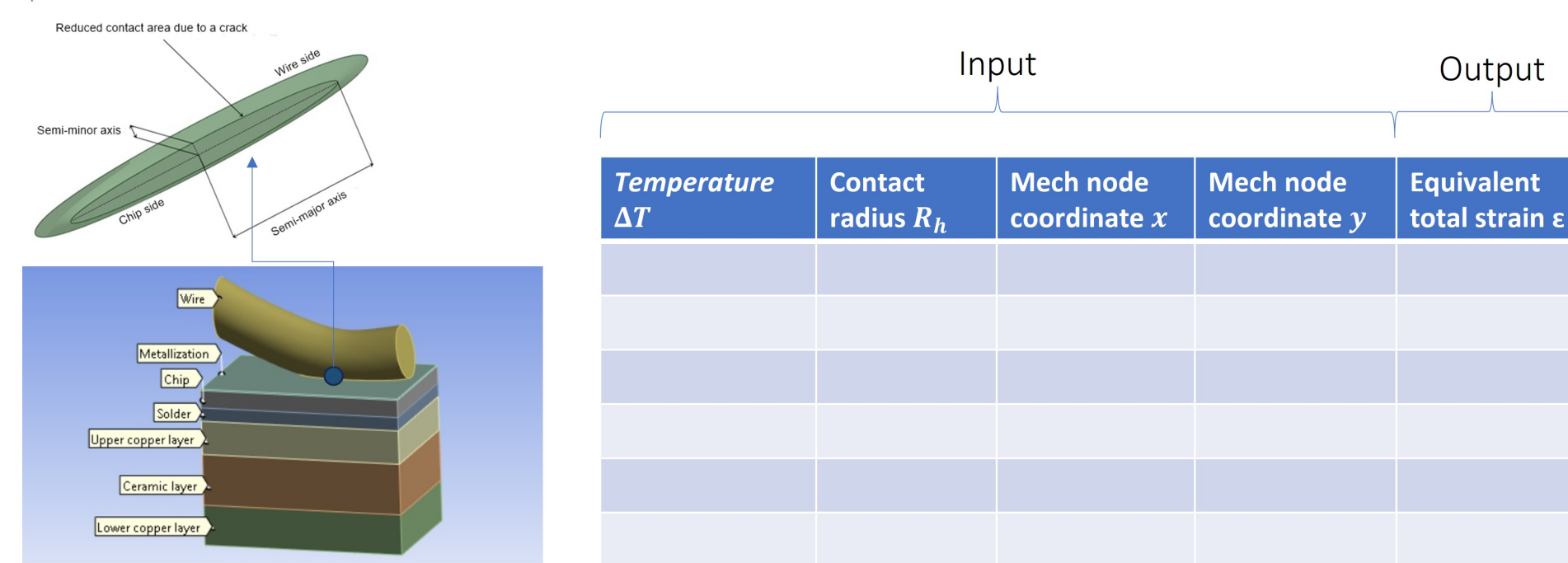


- This approach handles in-distribution predictions (left), interpolation (middle) and extrapolation (right).



4. Surrogates for Simulations

- Frequent numerical simulations are required, drastically increasing computational time. Data-driven metamodels are used as a faster alternative.

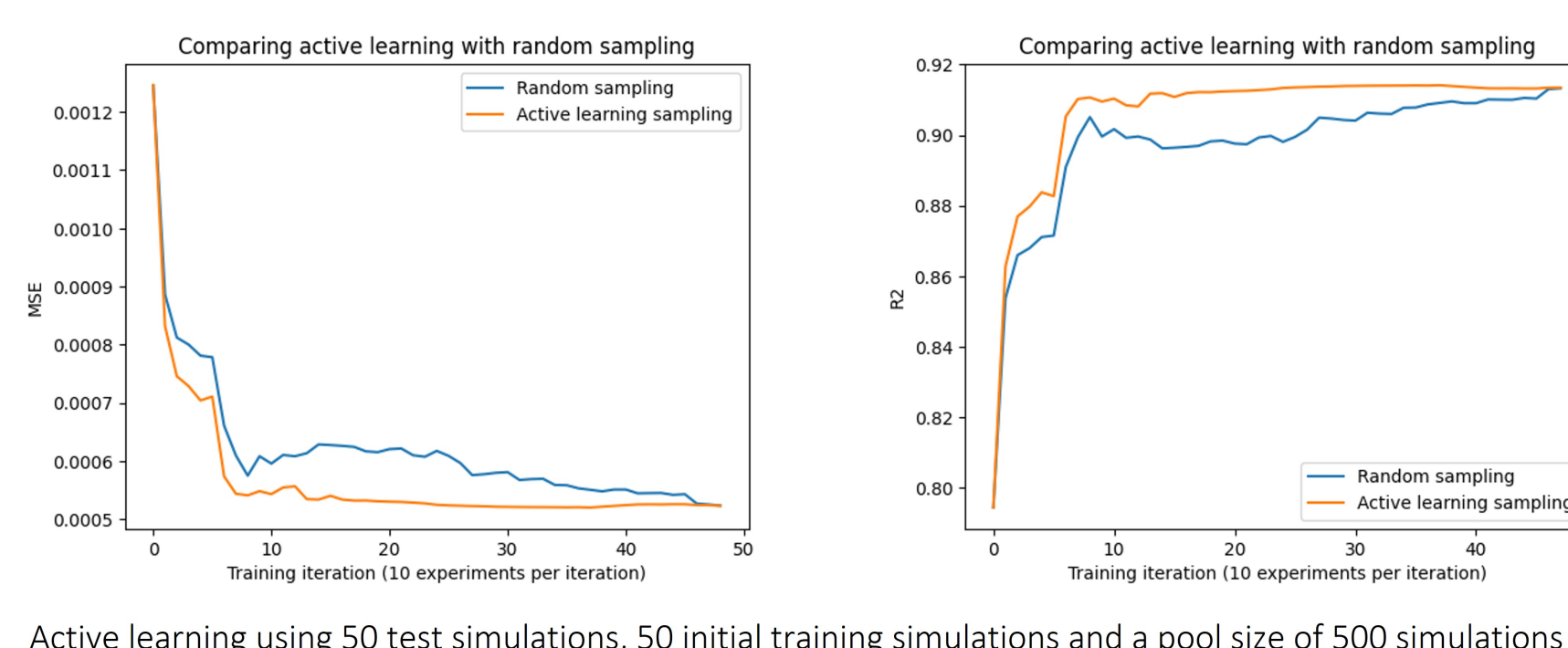
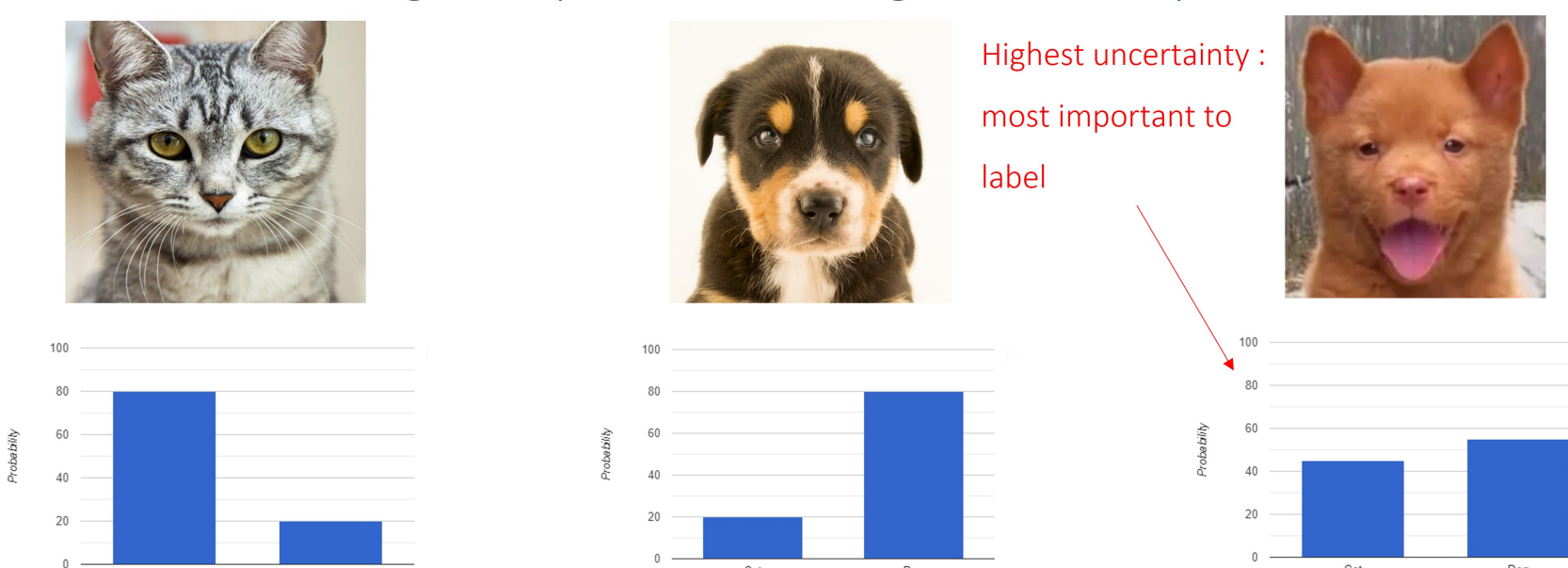


- Tree-based models are strong candidates due to their decision-based regression, while K-NN models offer competitive performance both statistically and computationally.

Models/Metrics	MSE (10 ⁻³)	MAE (10 ⁻²)	R ²	Fitting time (s)	Inference time (ms)
Linear	1.851	2.329	0.6	0.091	0
Regularization (linear)	1.851	2.329	0.6	1.891	0
Tree-based	0.175	0.463	0.962	673.375	0.211
Non-parametric	0.475	0.769	0.897	0.422	0.010
Neural network	0.438	0.829	0.905	991.052	0.022

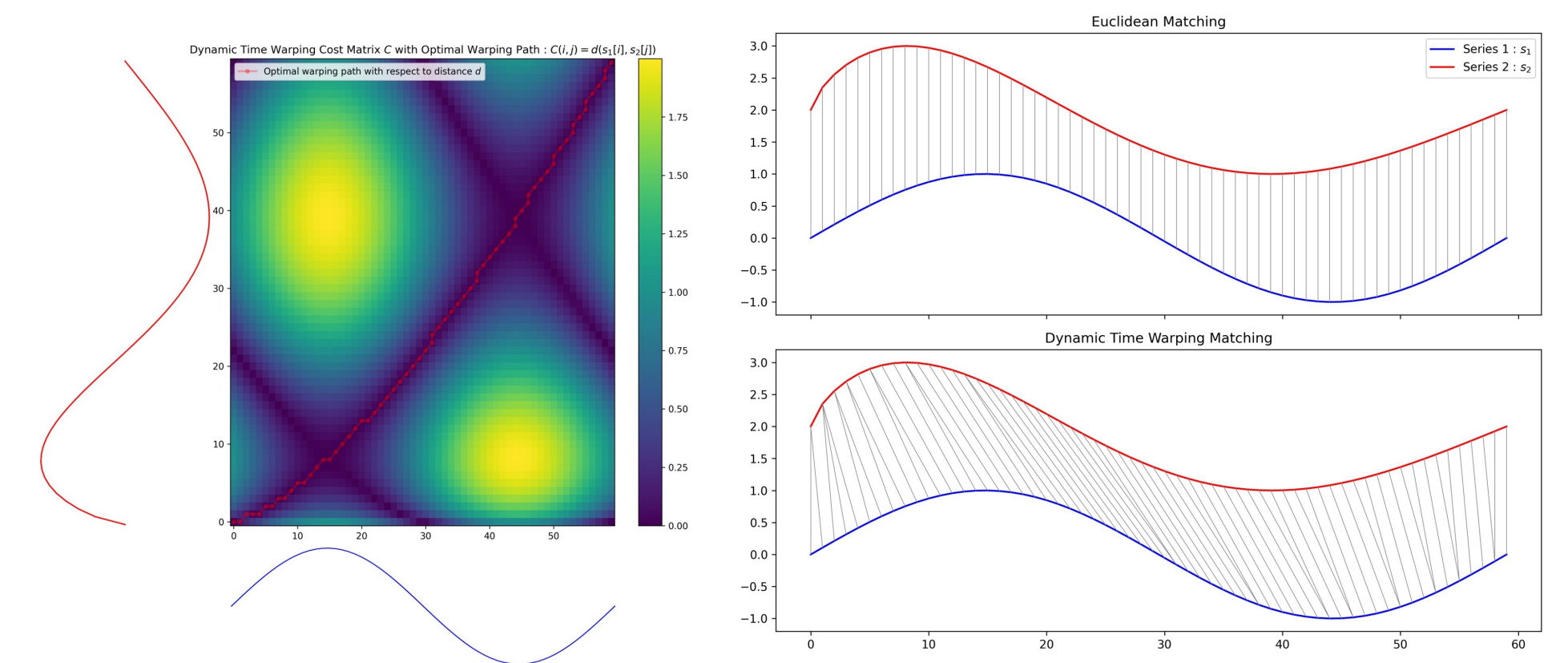
- Active learning is utilized to optimize the choice of simulations. Uncertainty is taken as the variance of an ensemble of predictors.

Active learning example : which image is more important to label?

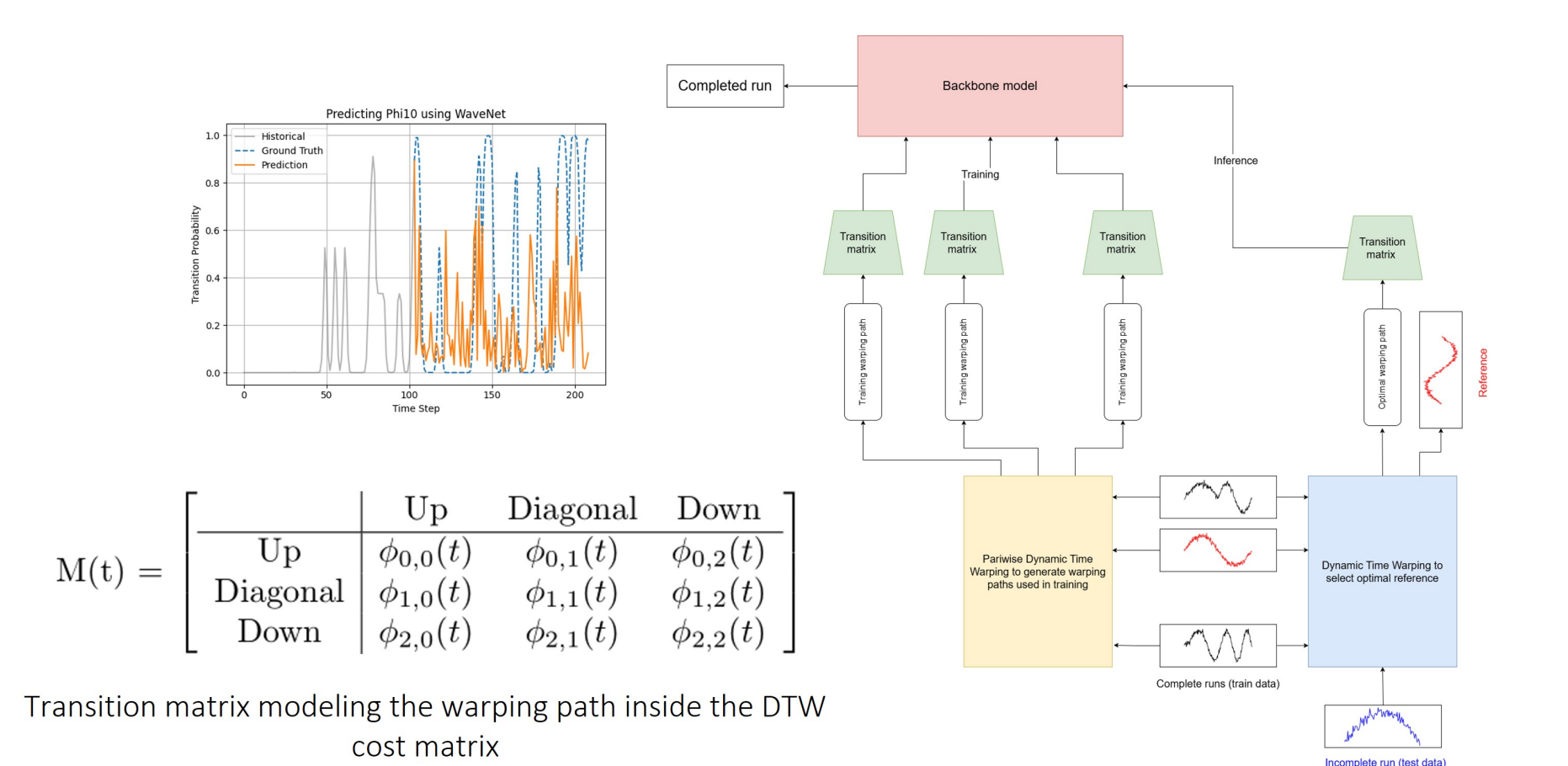


5. Forecasts with Incomplete Runs

- BED-Time: a time series forecasting model which accounts for warping : a realization f_{θ_1} parametrized by θ_1 is a non-linear transformation in time g_{θ_1} (warping) of a reference h : $f_{\theta_1}(t) = h(g_{\theta_1}(t))$.



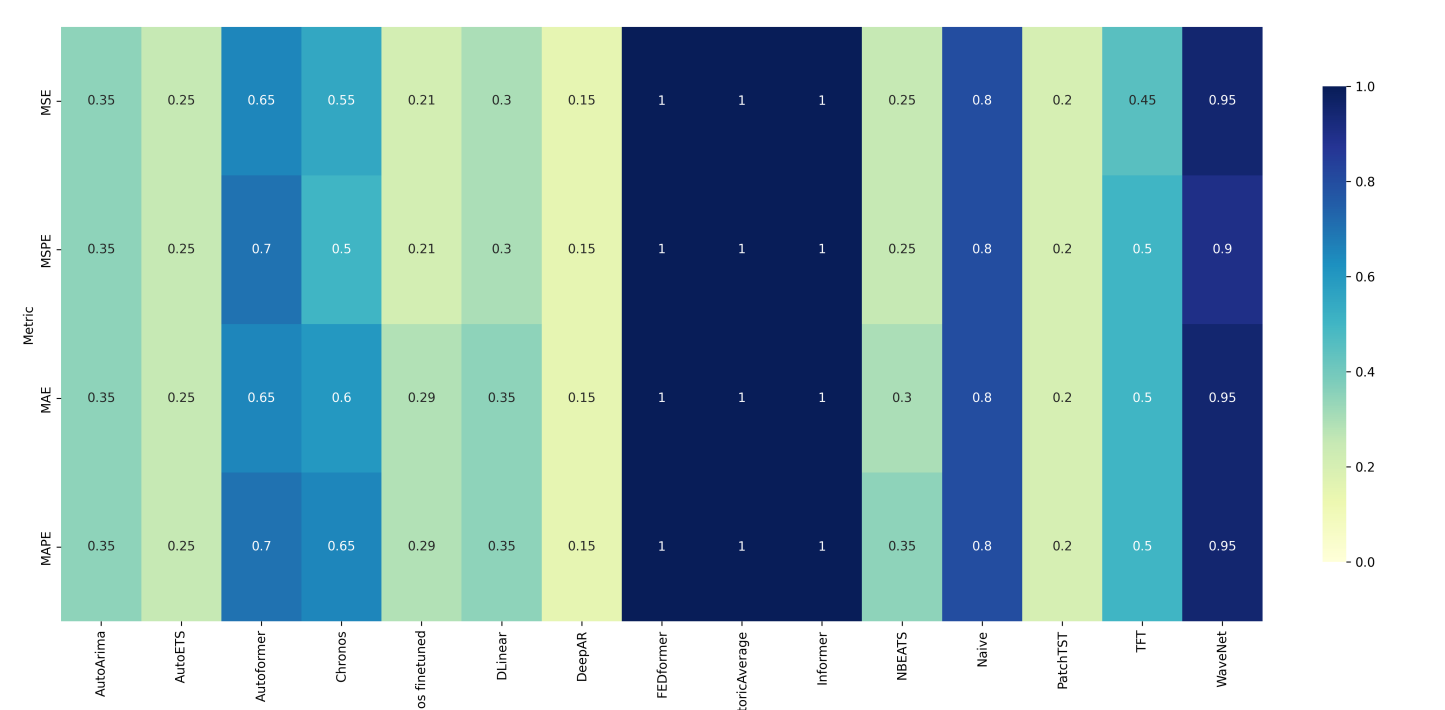
- A time series matching algorithm (Dynamic Time Warping) is used to find optimal matching. The optimal warping path is modeled using a time-inhomogeneous Markov chain (transition matrix $M(t)$).



$$M(t) = \begin{bmatrix} \text{Up} & \text{Diagonal} & \text{Down} \\ \phi_{0,0}(t) & \phi_{0,1}(t) & \phi_{0,2}(t) \\ \text{Diagonal} & \phi_{1,0}(t) & \phi_{1,1}(t) & \phi_{1,2}(t) \\ \text{Down} & \phi_{2,0}(t) & \phi_{2,1}(t) & \phi_{2,2}(t) \end{bmatrix}$$

Transition matrix modeling the warping path inside the DTW cost matrix

- BED-Time improves significantly on SOTA Transformer-based models, shown by the gains-ratio matrix which indicates how many times BED-time improves on the baseline.



References

[Dor19] N. Dornic. "Elaboration et comparaison de deux modes de durée de vie des fils d'interconnexion des modules de puissance, l'un basé sur les déformations et l'autre sur les dégradations". PhD thesis. 2019.

[Hal+25] A. Halouani et al. "Effect of load sequence interaction for low T_j's on the reliability of bonded aluminum wires in IGBTs". In: *Microelectronics Reliability* 171 (2025), p. 115793.

[Mas+11] A. Masson et al. "High-temperature die-attaches for SiC power devices". In: *Proceedings of the 2011 14th European Conference on Power Electronics and Applications*. 2011, pp. 1–10.

[Sch+12] O. Schilling et al. "Power cycling testing and FE modelling focussed on Al wire bond fatigue in high power IGBT modules". In: *Microelectronics Reliability* 52.9 (2012), pp. 2347–2352.

[Tho+08] M. Thoben et al. "From vehicle drive cycle to reliability testing of Power Modules for hybrid vehicle inverter". In: May 2008.